100 kPa On-Chip Temperature Compensated & Calibrated Silicon Pressure Sensors

MPX2102
MPXV2102G
SERIES

Motorola Preferred Device

0 to 100 kPa (0 to 14.5 psi)
40 mV FULL SCALE SPAN
(TYPICAL)

The MPX2102/MPXV2102G series device is a silicon piezoresistive pressure sensor providing a highly accurate and linear voltage output — directly proportional to the applied pressure. The sensor is a single, monolithic silicon diaphragm with the strain gauge and a thin–film resistor network integrated on–chip. The chip is laser trimmed for precise span and offset calibration and temperature compensation.

Features

- Temperature Compensated Over 0°C to +85°C
- Easy–to–Use Chip Carrier Package Options
- Available in Absolute, Differential and Gauge Configurations
- Ratiometric to Supply Voltage

Application Examples

- Pump/Motor Controllers
- Robotics
- Level Indicators
- Medical Diagnostics
- Pressure Switching
- Barometers
- Altimeters

Figure 1 illustrates a block diagram of the internal circuitry on the stand–alone pressure sensor chip.

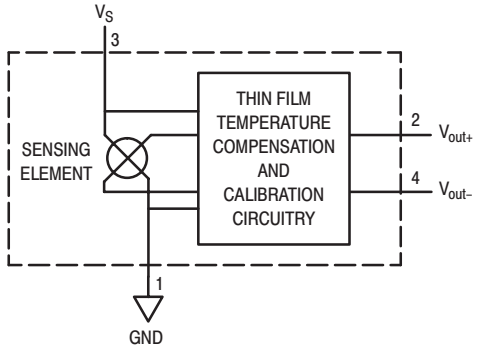


Figure 1. Temperature Compensated Pressure Sensor Schematic

VOLTAGE OUTPUT versus APPLIED DIFFERENTIAL PRESSURE

The differential voltage output of the sensor is directly proportional to the differential pressure applied.

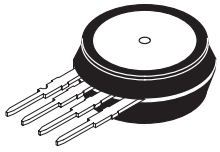
The absolute sensor has a built–in reference vacuum. The output voltage will decrease as vacuum, relative to ambient, is drawn on the pressure (P1) side.

The output voltage of the differential or gauge sensor increases with increasing pressure applied to the pressure (P1) side relative to the vacuum (P2) side. Similarly, output voltage increases as increasing vacuum is applied to the vacuum (P2) side relative to the pressure (P1) side.

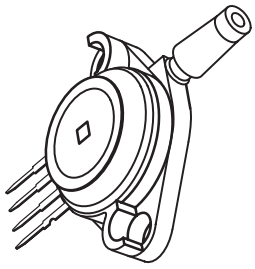
Preferred devices are Motorola recommended choices for future use and best overall value.

REV 2

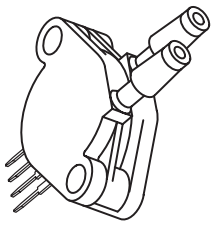
UNIBODY PACKAGE



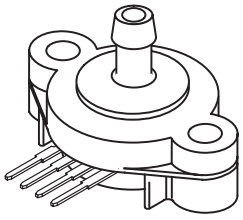
MPX2102A/D
CASE 344



MPX2102AP/GP
CASE 344B



MPX2102DP
CASE 344C

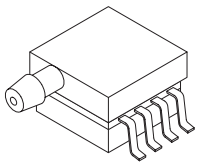


MPX2102ASX/GSX
CASE 344F

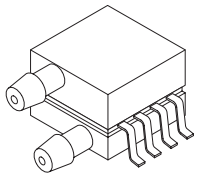
PIN NUMBER			
1	Gnd	3	V_S
2	$+V_{out}$	4	$-V_{out}$

NOTE: Pin 1 is noted by the notch in the lead.

SMALL OUTLINE PACKAGE
SURFACE MOUNT



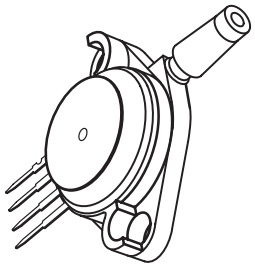
MPXV2102GP
CASE 1369



MPXV2102DP
CASE 1351

PIN NUMBER			
1	Gnd	5	N/C
2	$+V_{out}$	6	N/C
3	V_S	7	N/C
4	$-V_{out}$	8	N/C

NOTE: Pin 1 is noted by the notch in the lead.



MPX2102GVP
CASE 344D

MAXIMUM RATINGS(NOTE)

Rating	Symbol	Value	Unit
Maximum Pressure (P1 > P2)	P_{max}	400	kPa
Storage Temperature	T_{stg}	–40 to +125	°C
Operating Temperature	T_A	–40 to +125	°C

NOTE: Exposure beyond the specified limits may cause permanent damage or degradation to the device.

OPERATING CHARACTERISTICS (V_S = 10 Vdc, T_A = 25°C unless otherwise noted, P1 > P2)

Characteristic		Symbol	Min	Typ	Max	Unit
Pressure Range(1)		P_{OP}	0	—	100	kPa
Supply Voltage(2)		V_S	—	10	16	Vdc
Supply Current		I_o	—	6.0	—	mAdc
Full Scale Span(3)		V_{FSS}	38.5	40	41.5	mV
Offset(4)	MPX2102D Series MPX2102A Series	V_{off}	–1.0 –2.0	— —	1.0 2.0	mV
Sensitivity		ΔV/ΔP	—	0.4	—	mV/kPa
Linearity(5)	MPX2102D Series MPX2102A Series	—	— —	–0.6 –1.0	— —	0.4 1.0	%V_{FSS}
Pressure Hysteresis(5) (0 to 100 kPa)		—	—	±0.1	—	%V_{FSS}
Temperature Hysteresis(5) (–40°C to +125°C)		—	—	±0.5	—	%V_{FSS}
Temperature Effect on Full Scale Span(5)		TCV_{FSS}	–2.0	—	2.0	%V_{FSS}
Temperature Effect on Offset(5)		TCV_{off}	–1.0	—	1.0	mV
Input Impedance		Z_{in}	1000	—	2500	Ω
Output Impedance		Z_{out}	1400	—	3000	Ω
Response Time(6) (10% to 90%)		t_R	—	1.0	—	ms
Warm–Up		—	—	20	—	ms
Offset Stability(7)		—	—	±0.5	—	%V_{FSS}

NOTES:
1. 1.0 kPa (kiloPascal) equals 0.145 psi.
2. Device is ratiometric within this specified excitation range. Operating the device above the specified excitation range may induce additional error due to device self–heating.
3. Full Scale Span (V_{FSS}) is defined as the algebraic difference between the output voltage at full rated pressure and the output voltage at the minimum rated pressure.
4. Offset (V_{off}) is defined as the output voltage at the minimum rated pressure.
5. Accuracy (error budget) consists of the following:
   - Linearity: Output deviation from a straight line relationship with pressure, using end point method, over the specified pressure range.
   - Temperature Hysteresis: Output deviation at any temperature within the operating temperature range, after the temperature is cycled to and from the minimum or maximum operating temperature points, with zero differential pressure applied.
   - Pressure Hysteresis: Output deviation at any pressure within the specified range, when this pressure is cycled to and from the minimum or maximum rated pressure, at 25°C.
   - TcSpan: Output deviation at full rated pressure over the temperature range of 0 to 85°C, relative to 25°C.
   - TcOffset: Output deviation with minimum rated pressure applied, over the temperature range of 0 to 85°C, relative to 25°C.
6. Response Time is defined as the time for the incremental change in the output to go from 10% to 90% of its final value when subjected to a specified step change in pressure.
7. Offset stability is the product's output deviation when subjected to 1000 hours of Pulsed Pressure, Temperature Cycling with Bias Test.

LINEARITY

Linearity refers to how well a transducer's output follows the equation: $V_{out} = V_{off}$ + sensitivity x P over the operating pressure range. There are two basic methods for calculating nonlinearity: (1) end point straight line fit (see Figure 2) or (2) a least squares best line fit. While a least squares fit gives the "best case" linearity error (lower numerical value), the calculations required are burdensome.

Conversely, an end point fit will give the "worst case" error (often more desirable in error budget calculations) and the calculations are more straightforward for the user. Motorola's specified pressure sensor linearities are based on the end point straight line method measured at the midrange pressure.

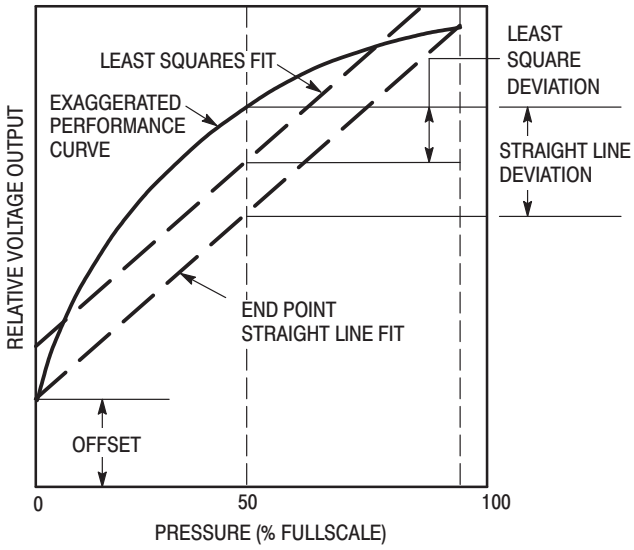


Figure 2. Linearity Specification Comparison

ON–CHIP TEMPERATURE COMPENSATION and CALIBRATION

Figure 3 shows the output characteristics of the MPX2102/MPXV2102G series at 25°C. The output is directly proportional to the differential pressure and is essentially a straight line.

The effects of temperature on Full Scale Span and Offset are very small and are shown under Operating Characteristics.

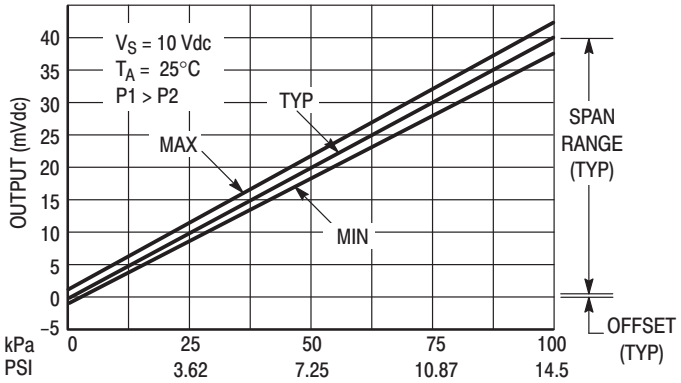


Figure 3. Output versus Pressure Differential

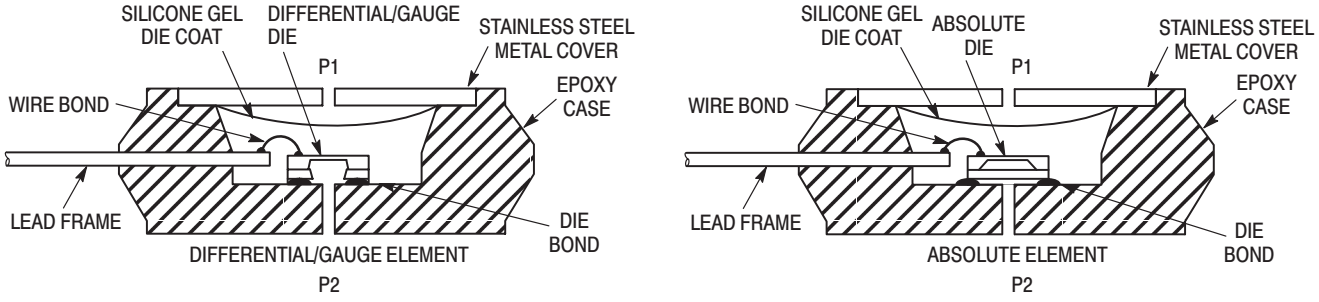


Figure 4. Cross–Sectional Diagrams (Not to Scale)

Figure 4 illustrates the absolute sensing configuration (right) and the differential or gauge configuration in the basic chip carrier (Case 344). A silicone gel isolates the die surface and wire bonds from the environment, while allowing the pressure signal to be transmitted to the silicon diaphragm.

The MPX2102/MPXV2102G series pressure sensor operating characteristics and internal reliability and qualification tests are based on use of dry air as the pressure media. Media other than dry air may have adverse effects on sensor performance and long term reliability. Contact the factory for information regarding media compatibility in your application.

PRESSURE (P1)/VACUUM (P2) SIDE IDENTIFICATION TABLE

Motorola designates the two sides of the pressure sensor as the Pressure (P1) side and the Vacuum (P2) side. The Pressure (P1) side is the side containing the silicone gel which isolates the die. The differential or gauge sensor is designed to operate with positive differential pressure applied, P1 > P2. The absolute sensor is designed for vacuum applied to P1 side.

The Pressure (P1) side may be identified by using the table below:

Part Number		Case Type	Pressure (P1) Side Identifier
MPX2102A	MPX2102D	344	Stainless Steel Cap
MPX2102DP		344C	Side with Part Marking
MPX2102AP	MPX2102GP	344B	Side with Port Attached
MPX2102GVP		344D	Stainless Steel Cap
MPX2102ASX	MPX2102GSX	344F	Side with Port Attached
MPXV2102GP		1369	Side with Port Attached
MPXV2102DP		1351	Side with Part Marking

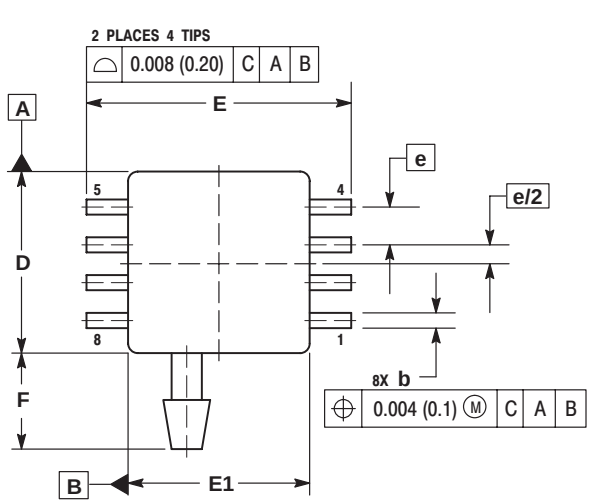
ORDERING INFORMATION — UNIBODY PACKAGE (MPX2102 SERIES)

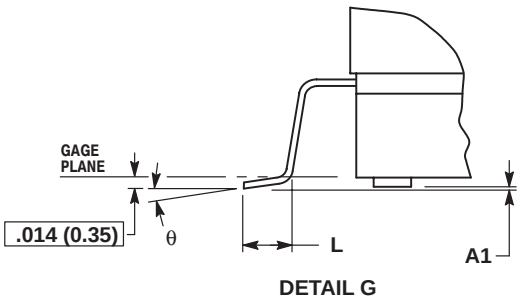
Device Type	Options	Case Type	MPX Series	
			Order Number	Device Marking
Basic Element	Absolute, Differential	344	MPX2102A MPX2102D	MPX2102A MPX2102D
Ported Elements	Differential, Dual Port	344C	MPX2102DP	MPX2102DP
	Absolute, Gauge	344B	MPX2102AP MPX2102GP	MPX2102AP MPX2102GP
	Absolute, Gauge Axial	344F	MPX2102ASX MPX2102GSX	MPX2102A MPX2102D
	Gauge, Vacuum	344D	MPX2102GVP	MPX2102GVP

ORDERING INFORMATION — SMALL OUTLINE PACKAGE (MPXV2102G SERIES)

Device Type	Options	Case No.	MPX Series Order No.	Packing Options	Marking
Ported Elements	Gauge, Side Port, SMT	1369	MPXV2102GP	Trays	MPXV2102G
	Differential, Dual Port, SMT	1351	MPXV2102DP	Trays	MPXV2102G

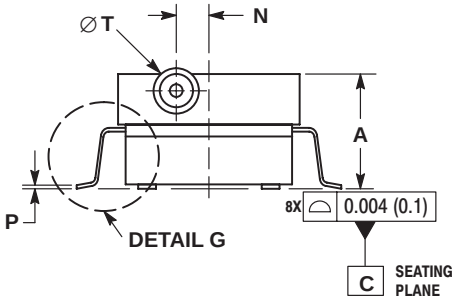
SMALL OUTLINE PACKAGE DIMENSIONS

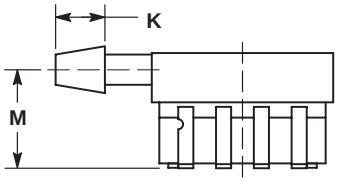




DETAIL G

NOTES:
1. CONTROLLING DIMENSION: INCH.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M–1994.
3. DIMENSIONS "D" AND "E1" DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.006 (0.152) PER SIDE.
4. DIMENSION "b" DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.008 (0.203) MAXIMUM.

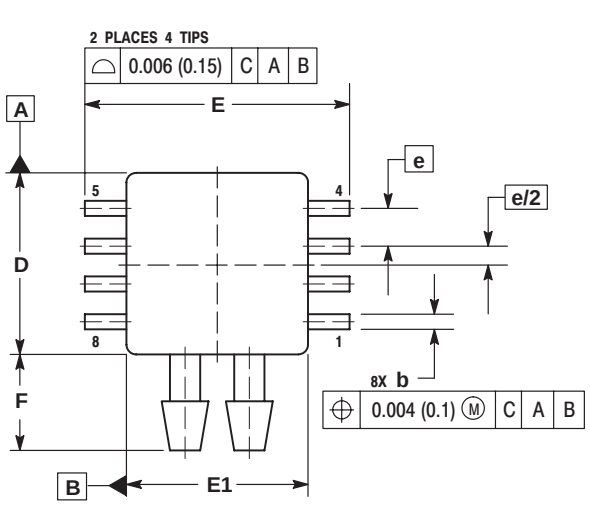


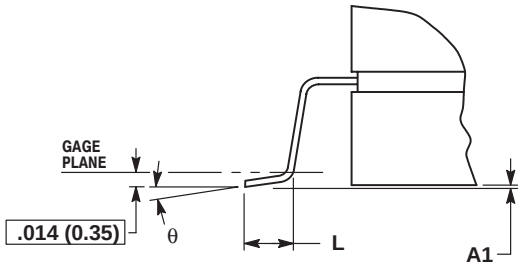


DIM	INCHES MIN	INCHES MAX	MILLIMETERS MIN	MILLIMETERS MAX
A	0.300	0.330	7.11	7.62
A1	0.002	0.010	0.05	0.25
b	0.038	0.042	0.96	1.07
D	0.465	0.485	11.81	12.32
E	0.717 BSC		18.21 BSC	
E1	0.465	0.485	11.81	12.32
e	0.100 BSC		2.54 BSC	
F	0.245	0.255	6.22	6.47
K	0.120	0.130	3.05	3.30
L	0.061	0.071	1.55	1.80
M	0.270	0.290	6.86	7.36
N	0.080	0.090	2.03	2.28
P	0.009	0.011	0.23	0.28
T	0.115	0.125	2.92	3.17
θ	0°	7°	0°	7°

CASE 1369–01
ISSUE O

SMALL OUTLINE PACKAGE DIMENSIONS—CONTINUED



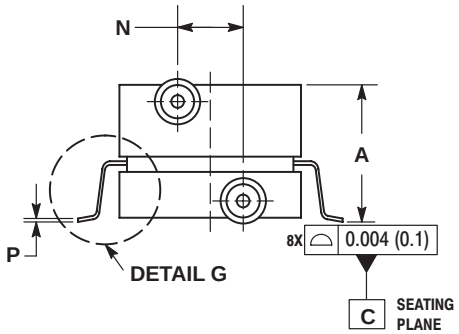


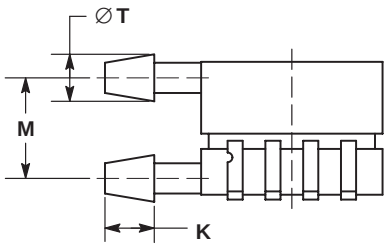
DETAIL G

STYLE 1:
PIN 1. GND
2. +Vout
3. Vs
4. –Vout
5. N/C
6. N/C
7. N/C
8. N/C

STYLE 2:
PIN 1. N/C
2. Vs
3. GND
4. Vout
5. N/C
6. N/C
7. N/C
8. N/C

NOTES:
1. CONTROLLING DIMENSION: INCH.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M–1994.
3. DIMENSIONS "D" AND "E1" DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.006 (0.152) PER SIDE.
4. DIMENSION "b" DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.008 (0.203) MAXIMUM.

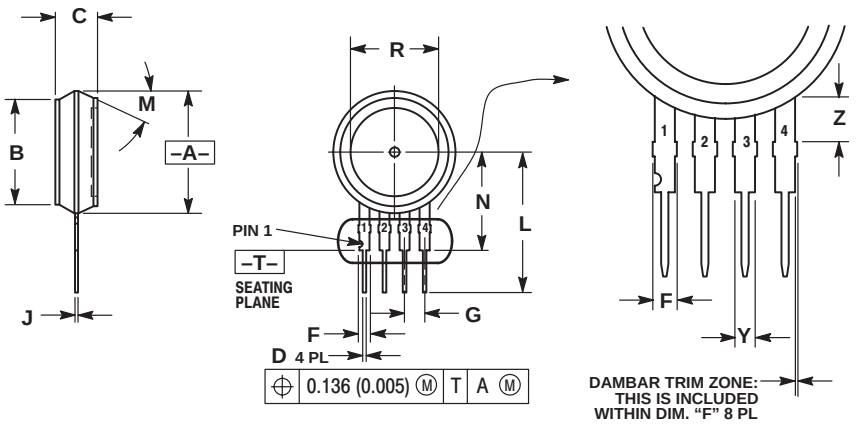




DIM	INCHES MIN	INCHES MAX	MILLIMETERS MIN	MILLIMETERS MAX
A	0.370	0.390	9.39	9.91
A1	0.002	0.010	0.05	0.25
b	0.038	0.042	0.96	1.07
D	0.465	0.485	11.81	12.32
E	0.680	0.700	17.27	17.78
E1	0.465	0.485	11.81	12.32
e	0.100 BSC		2.54 BSC	
F	0.240	0.260	6.10	6.60
K	0.115	0.135	2.92	3.43
L	0.040	0.060	1.02	1.52
M	0.270	0.290	6.86	7.37
N	0.160	0.180	4.06	4.57
P	0.009	0.011	0.23	0.28
T	0.110	0.130	2.79	3.30
θ	0°	7°	0°	7°

CASE 1351–01
ISSUE O

UNIBODY PACKAGE DIMENSIONS



NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION –A– IS INCLUSIVE OF THE MOLD STOP RING. MOLD STOP RING NOT TO EXCEED 16.00 (0.630).

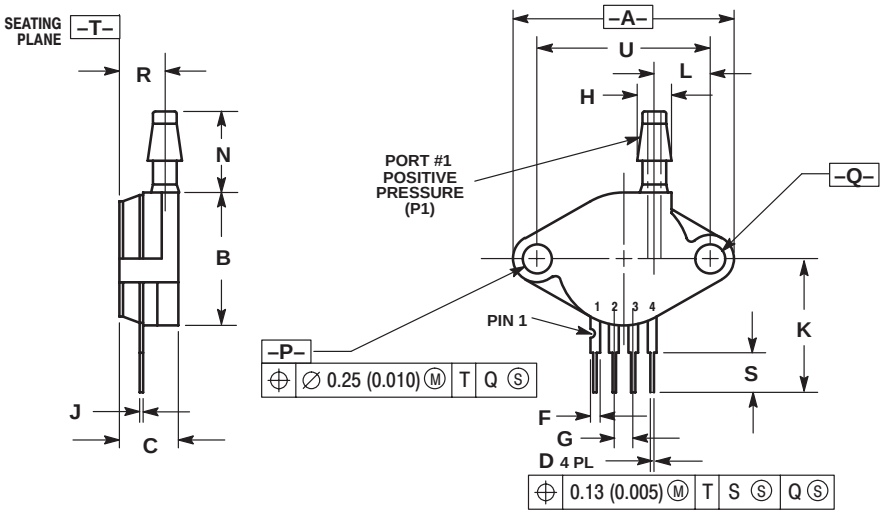
	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.595	0.630	15.11	16.00
B	0.514	0.534	13.06	13.56
C	0.200	0.220	5.08	5.59
D	0.016	0.020	0.41	0.51
F	0.048	0.064	1.22	1.63
G	0.100 BSC		2.54 BSC	
J	0.014	0.016	0.36	0.40
L	0.695	0.725	17.65	18.42
M	30° NOM		30° NOM	
N	0.475	0.495	12.07	12.57
R	0.430	0.450	10.92	11.43
Y	0.048	0.052	1.22	1.32
Z	0.106	0.118	2.68	3.00

STYLE 1:
PIN 1. GROUND
2. + OUTPUT
3. + SUPPLY
4. – OUTPUT

STYLE 2:
PIN 1. V_{CC}
2. – SUPPLY
3. + SUPPLY
4. GROUND

STYLE 3:
PIN 1. GND
2. –VOUT
3. VS
4. +VOUT

CASE 344–15
ISSUE Z



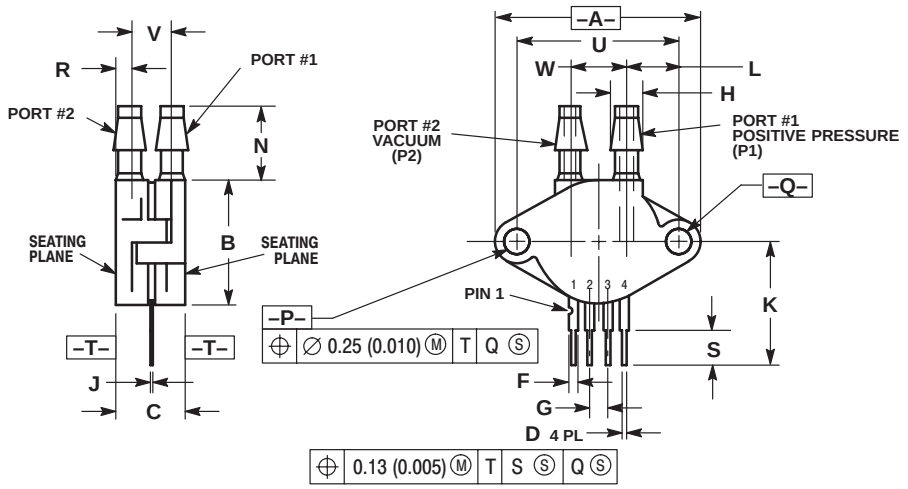
NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5, 1982.
2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	1.145	1.175	29.08	29.85
B	0.685	0.715	17.40	18.16
C	0.305	0.325	7.75	8.26
D	0.016	0.020	0.41	0.51
F	0.048	0.064	1.22	1.63
G	0.100 BSC		2.54 BSC	
H	0.182	0.194	4.62	4.93
J	0.014	0.016	0.36	0.41
K	0.695	0.725	17.65	18.42
L	0.290	0.300	7.37	7.62
N	0.420	0.440	10.67	11.18
P	0.153	0.159	3.89	4.04
Q	0.153	0.159	3.89	4.04
R	0.230	0.250	5.84	6.35
S	0.220	0.240	5.59	6.10
U	0.910 BSC		23.11 BSC	

STYLE 1:
PIN 1. GROUND
2. + OUTPUT
3. + SUPPLY
4. – OUTPUT

CASE 344B–01
ISSUE B

UNIBODY PACKAGE DIMENSIONS — CONTINUED

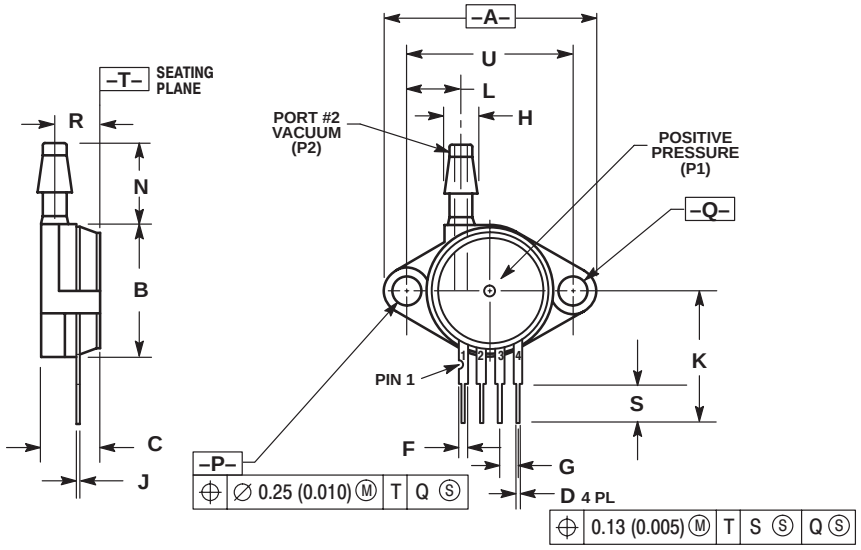


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	1.145	1.175	29.08	29.85
B	0.685	0.715	17.40	18.16
C	0.405	0.435	10.29	11.05
D	0.016	0.020	0.41	0.51
F	0.048	0.064	1.22	1.63
G	0.100 BSC		2.54 BSC	
H	0.182	0.194	4.62	4.93
J	0.014	0.016	0.36	0.41
K	0.695	0.725	17.65	18.42
L	0.290	0.300	7.37	7.62
N	0.420	0.440	10.67	11.18
P	0.153	0.159	3.89	4.04
Q	0.153	0.159	3.89	4.04
R	0.063	0.083	1.60	2.11
S	0.220	0.240	5.59	6.10
U	0.910 BSC		23.11 BSC	
V	0.248	0.278	6.30	7.06
W	0.310	0.330	7.87	8.38

STYLE 1:
PIN 1. GROUND
2. + OUTPUT
3. + SUPPLY
4. – OUTPUT

CASE 344C–01
ISSUE B



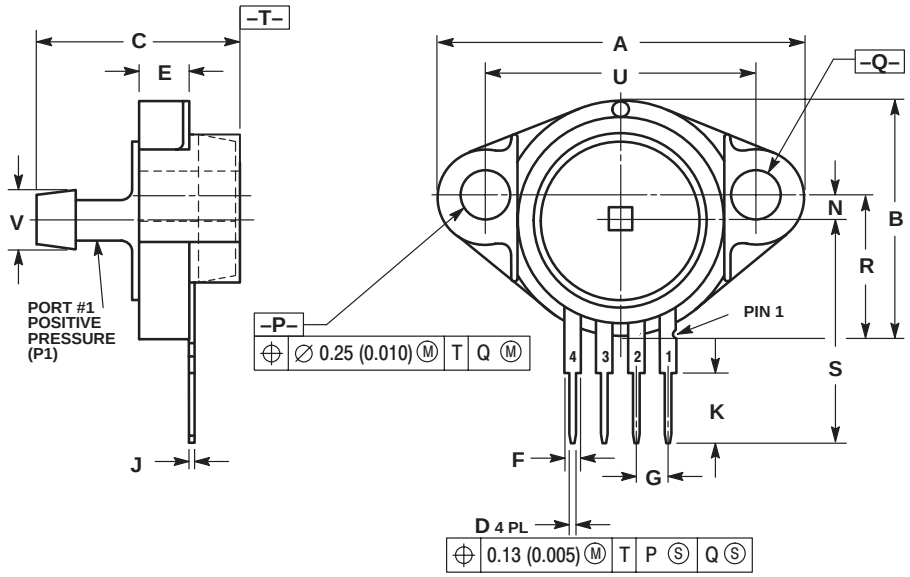
NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5, 1982.
2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	1.145	1.175	29.08	29.85
B	0.685	0.715	17.40	18.16
C	0.305	0.325	7.75	8.26
D	0.016	0.020	0.41	0.51
F	0.048	0.064	1.22	1.63
G	0.100 BSC		2.54 BSC	
H	0.182	0.194	4.62	4.93
J	0.014	0.016	0.36	0.41
K	0.695	0.725	17.65	18.42
L	0.290	0.300	7.37	7.62
N	0.420	0.440	10.67	11.18
P	0.153	0.159	3.89	4.04
Q	0.153	0.158	3.89	4.04
R	0.230	0.250	5.84	6.35
S	0.220	0.240	5.59	6.10
U	0.910 BSC		23.11 BSC	

STYLE 1:
PIN 1. GROUND
2. + OUTPUT
3. + SUPPLY
4. – OUTPUT

CASE 344D–01
ISSUE B

UNIBODY PACKAGE DIMENSIONS — CONTINUED



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	1.080	1.120	27.43	28.45
B	0.740	0.760	18.80	19.30
C	0.630	0.650	16.00	16.51
D	0.016	0.020	0.41	0.51
E	0.160	0.180	4.06	4.57
F	0.048	0.064	1.22	1.63
G	0.100 BSC		2.54 BSC	
J	0.014	0.016	0.36	0.41
K	0.220	0.240	5.59	6.10
N	0.070	0.080	1.78	2.03
P	0.150	0.160	3.81	4.06
Q	0.150	0.160	3.81	4.06
R	0.440	0.460	11.18	11.68
S	0.695	0.725	17.65	18.42
U	0.840	0.860	21.34	21.84
V	0.182	0.194	4.62	4.92

STYLE 1:
PIN 1. GROUND
2. V (+) OUT
3. V SUPPLY
4. V (–) OUT

CASE 344F–01
ISSUE B

NOTES

NOTES

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